

# GaAs INTEGRATED CIRCUIT $\mu$ PG2163T5N

## SPDT SWITCH FOR 2.4 GHz AND 6 GHz DUAL-BAND WIRELESS LAN

#### DESCRIPTION

The  $\mu$ PG2163T5N is GaAs MMIC SPDT (Single Pole Double Throw) switch which was developed for 2.4 GHz and 6 GHz dual-band wireless LAN. This device can operate frequency from 2.4 GHz band and 6 GHz band, having the low insertion loss and high isolation.

This device is housed in a 6-pin plastic TSON ( $\underline{T}$ hin  $\underline{S}$ mall  $\underline{O}$ ut-line  $\underline{N}$ on-leaded) package. And this package is able to high-density surface mounting.

#### **FEATURES**

Operating frequency : f = 2.4 to 2.5 GHz and 4.9 to 6.0 GHz
 Switch control voltage : V<sub>cont</sub> (H) = 2.8 to 5.0 V (3.0 V TYP.)
 : V<sub>cont</sub> (L) = -0.3 to 0.3 V (0 V TYP.)
 Low insertion loss : Lins1 = 0.40 dB TYP. @ f = 2.4 to 2.5 GHz, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V : Lins2 = 0.50 dB TYP. @ f = 4.9 to 6.0 GHz, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V : ISL1 = 38 dB TYP. @ f = 2.4 to 2.5 GHz, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V : ISL2 = 30 dB TYP. @ f = 4.9 to 6.0 GHz, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V : Handling power : P<sub>in</sub> (1 dB) = +31.0 dBm TYP. @ f = 2.5 GHz, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V

• High-density surface mounting: 6-pin plastic TSON package (1.5 × 1.5 × 0.37 mm)

#### **APPLICATIONS**

• Dual-band wireless LAN (IEEE802.11a + b/g)

#### ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2163T5N-E2	μPG2163T5N-E2-A	6-pin plastic TSON (Pb-Free)	G4X	Embossed tape 8 mm wide     Pin 1, 6 face the perforation side of the tape     Qty 3 kpcs/reel

: Pin (1 dB) = +29.0 dBm TYP. @ f = 6.0 GHz,  $V_{cont}(H) = 3.0 \text{ V}$ ,  $V_{cont}(L) = 0 \text{ V}$ 

Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order:  $\mu$ PG2163T5N

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

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Pin Name GND

 $V_{cont}2$ 

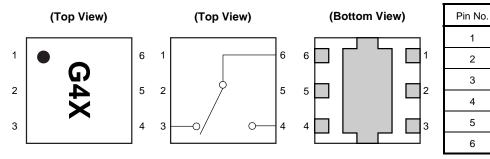
OUT2 (RX)

OUT1 (TX)

 $V_{\text{cont}}\mathbf{1}$ 

IN (ANT)

#### PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Remark Exposed pad: GND

## TRUTH TABLE

V <sub>cont</sub> 1	V <sub>cont</sub> 2	IN (ANT)-OUT1 (TX)	IN (ANT)-OUT2 (RX)	
High	Low	OFF	ON	
Low	High	ON	OFF	

# ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	Vcont	-6.0 to +6.0	V
Input Power	Pin	+32	dBm
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	Tstg	-55 to +135	°C

# RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	V <sub>cont (H)</sub>	2.8	3.0	5.0	V
Switch Control Voltage (L)	V <sub>cont (L)</sub>	-0.3	0	0.3	V
Operating Frequency 1	f1	2.4	-	2.5	GHz
Operating Frequency 2	f2	4.9	_	6.0	GHz

#### **ELECTRICAL CHARACTERISTICS**

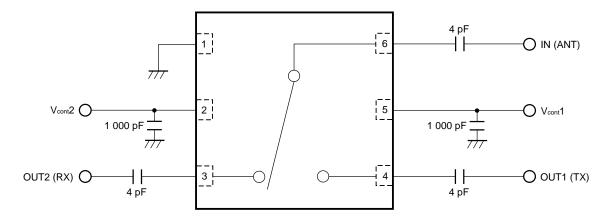
(TA = +25°C, V<sub>cont</sub> (H) = 3.0 V, V<sub>cont</sub> (L) = 0 V, Z<sub>0</sub> = 50  $\Omega$ , DC blocking capacitors = 4 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	f = 2.4 to 2.5 GHz	-	0.40	0.60	dB
Insertion Loss 2	Lins2	f = 4.9 to 6.0 GHz	-	0.50	0.80	dB
Isolation 1	ISL1	f = 2.4 to 2.5 GHz	35	38	-	dB
Isolation 2	ISL2	f = 4.9 to 6.0 GHz	27	30	-	dB
Input Return Loss 1	RLin1	f = 2.4 to 2.5 GHz	-	15	-	dB
Input Return Loss 2	RLin2	f = 4.9 to 6.0 GHz	-	15	-	dB
Output Return Loss 1	RLout1	f = 2.4 to 2.5 GHz	-	15	-	dB
Output Return Loss 2	RLout2	f = 4.9 to 6.0 GHz	-	15	-	dB
1 dB Loss Compression Input Power 1 Note	Pin (1 dB) 1	f = 2.4 to 2.5 GHz	-	+31.0	-	dBm
1 dB Loss Compression Input Power 2 Note	Pin (1 dB) 2	f = 4.9 to 6.0 GHz	-	+29.0	-	dBm
Input 3rd Order Distortion Intercept Point	IIP <sub>3</sub>		-	+55	ı	dBm
Switch Control Current	Icont			0.1	1.0	μА
Switch Control Speed	tsw	50% CTL to 90/10%	-	50	ı	ns

**Note** Pin (1 dB) is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution This device is used it is necessary to use DC blocking capacitors.

## **EVALUATION CIRCUIT**

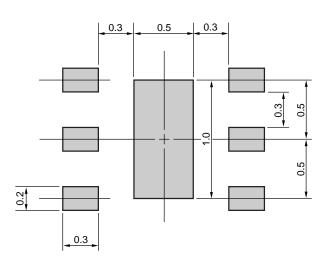


The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

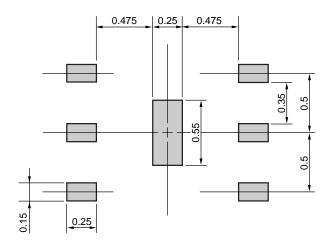
## MOUNTING PAD DIMENSIONS

# 6-PIN PLASTIC TSON (UNIT: mm)

## **MOUNTING PAD**



# **SOLDER PAD**

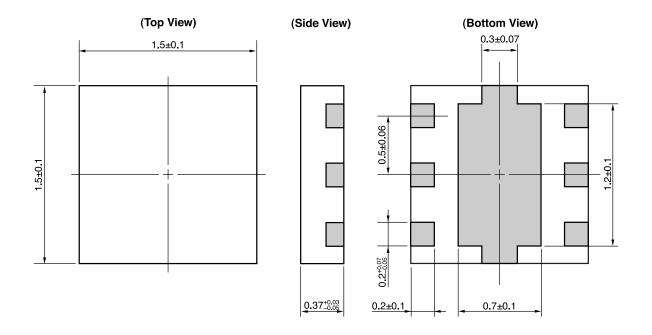


Solder thickness: 0.08 mm

**Remark** The mounting pad layouts in this document are for reference only.

# **PACKAGE DIMENSIONS**

6-PIN PLASTIC TSON (UNIT: mm)



#### RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	H\$350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

#### Caution

**GaAs Products** 

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

#### ▶ For further information, please contact

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PBB < 1000 PPM		Not De	etected
PBDE	< 1000 PPM	Not Detected	

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